

SOT1997-1

FBGA477, fine-pitch ball grid array package, 477 terminals,
0.75 mm pitch, 17 mm x 17 mm x 2.03 mm body

15 October 2018

Package information

1 Package summary

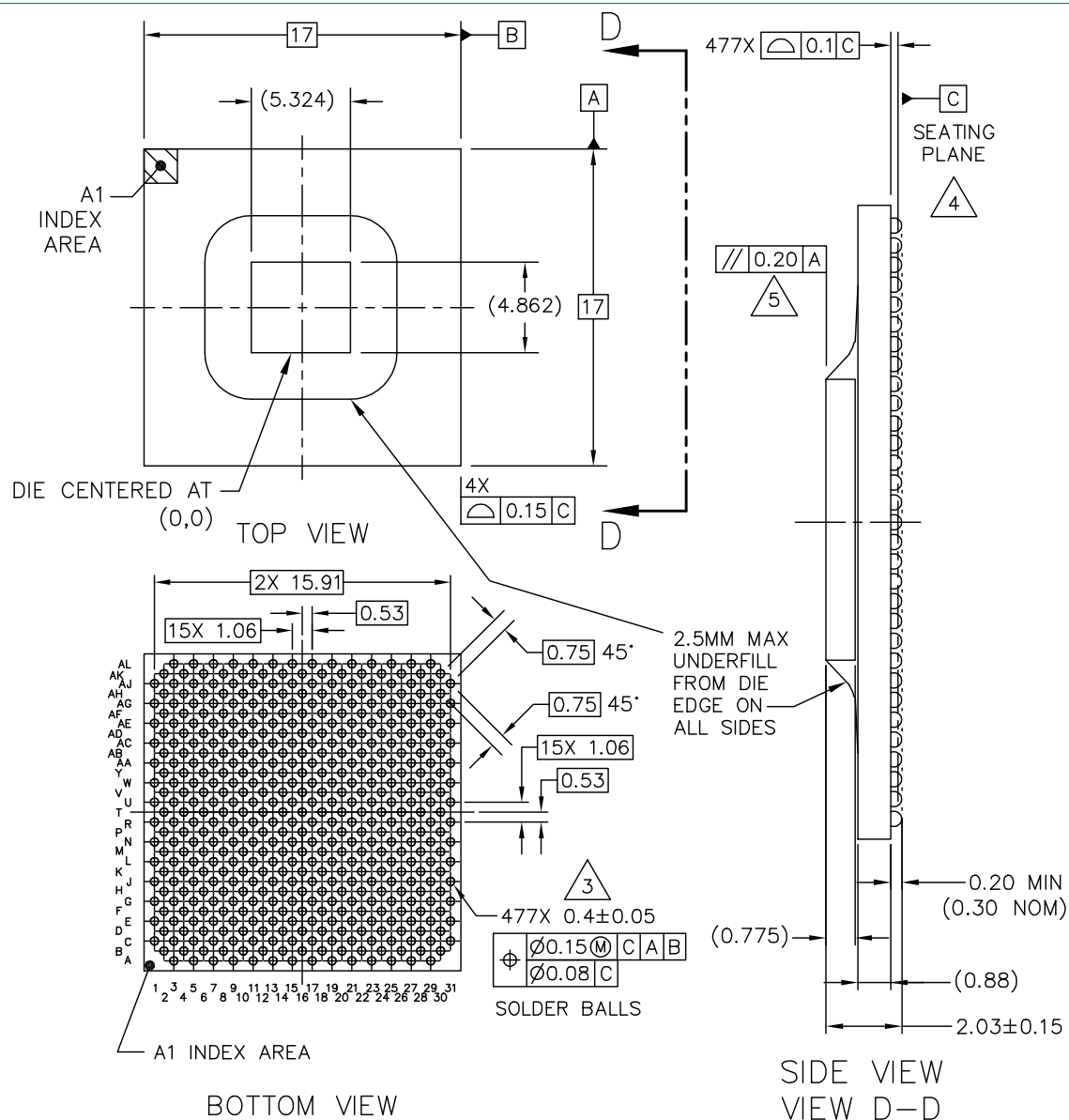
Terminal position code	B (bottom)
Package type descriptive code	FBGA477
Package style descriptive code	FBGA (fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	21-09-2018
Manufacturer package code	98ASA01325D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	17	-	mm
package width	-	17	-	mm
package height	-	2.03	-	mm
nominal pitch	-	0.75	-	mm
actual quantity of termination	-	477	-	



2 Package outline



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TITLE: FCPBGA, NO LID, 17 X 17 X 2.03 PKG, 0.75 MM PITCH, 477 I/O INTERSTITIAL	DOCUMENT NO: 98ASA01325D	REV: 0
	STANDARD: NON-JEDEC	
	SOT1997-1	21 SEP 2018

Figure 1. Package outline FBGA477 (SOT1997-1)

FBGA477, fine-pitch ball grid array package, 477 terminals, 0.75 mm pitch, 17 mm x 17 mm x 2.03 mm body

- NOTES:
- 1. ALL DIMENSIONS IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C. RAW BALL DIAMETER IS 0.4MM.
 - 4. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 - 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
 - 6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.

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		STANDARD: NON-JEDEC	
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Figure 2. Package outline note FBGA477 (SOT1997-1)

3 Legal information

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body

Contents

1 Package summary1
2 Package outline2
3 Legal information4